

A

B

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A

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| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

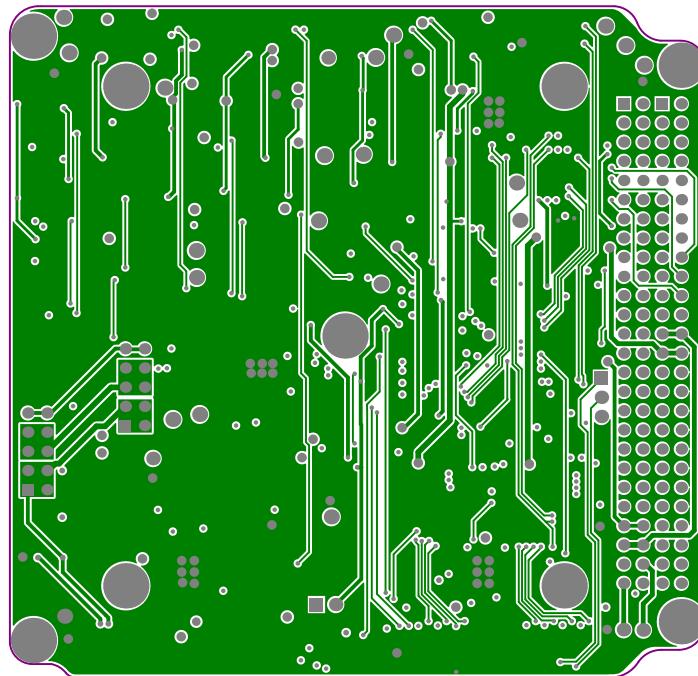
Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Top Layer | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | Project Code: EPS2 |
| Date: 23/10/2022 | Version: v0.2 |
| | Size: A4 |



A

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| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

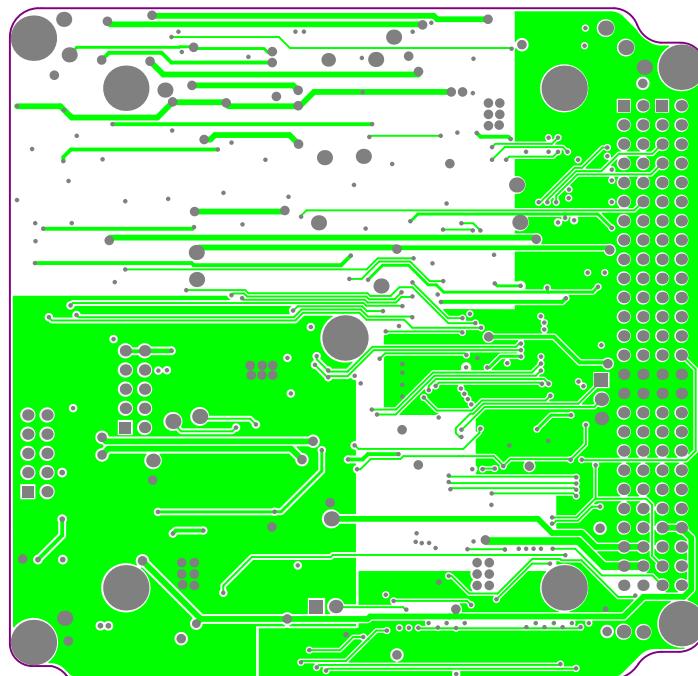
- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Signal Layer 1 | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | Project Code: EPS2 |
| Date: 23/10/2022 | Version: v0.2 |
| | Size: A4 |

A



B

C

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A

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D

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

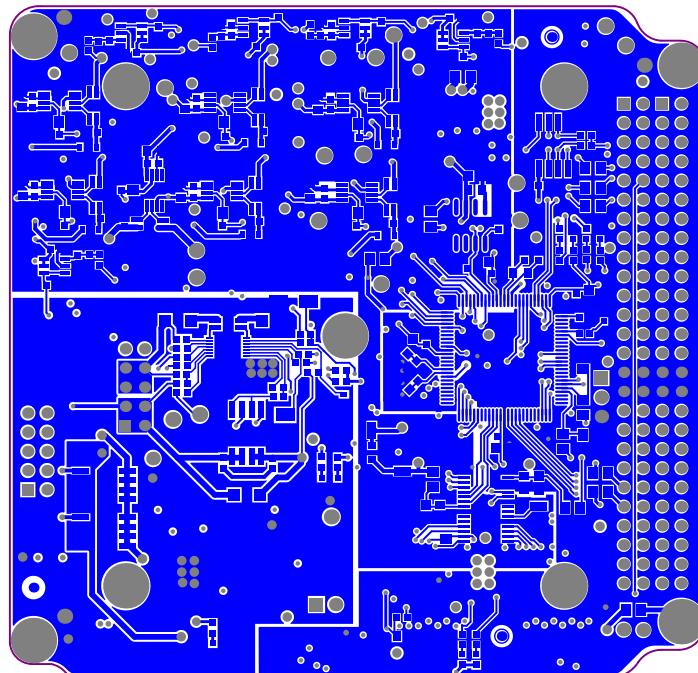
Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Signal Layer 2 | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | |
| Date: 23/10/2022 | Project Code: EPS2 |
| Version: v0.2 | Size: A4 |



| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Bottom Layer | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | Project Code: EPS2 |
| Date: 23/10/2022 | Version: v0.2 |
| | Size: A4 |

A

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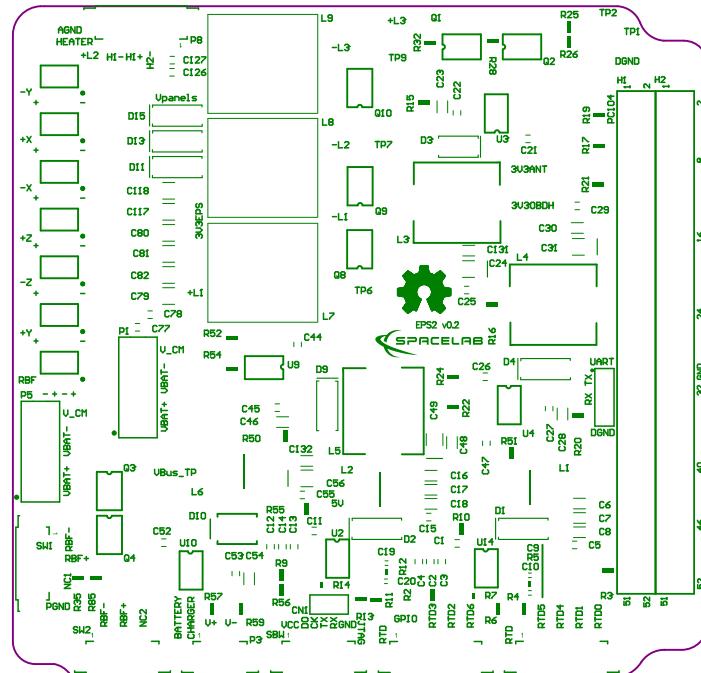
D

A

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| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina

Project: EPS2

Layer: Top Overlay

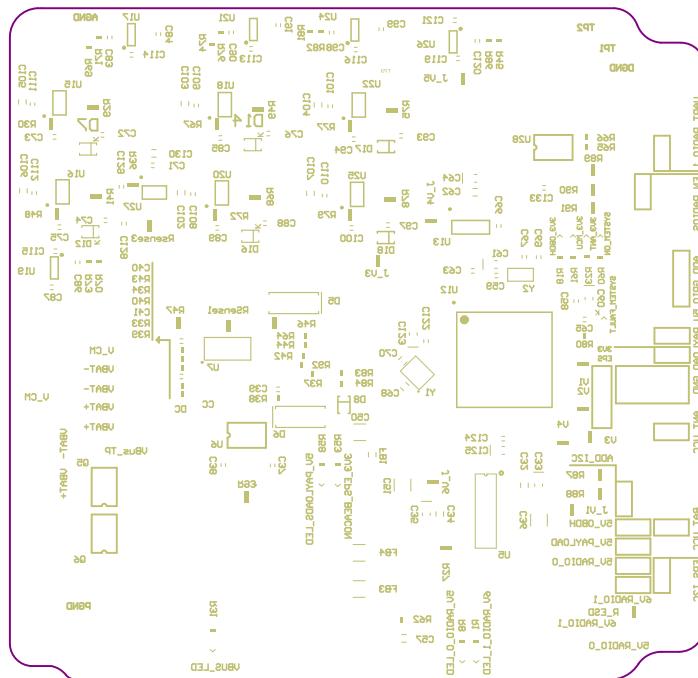
Designed by: Andre M. P. Mattos (based on FSat-I EPS) Project Code: EPS2

Date: 23/10/2022 Version: v0.2

Size: A4



A



B

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

C

Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

D

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|--|---------------|
| SpaceLab - Federal University of Santa Catarina | |
| Project: EPS2 | |
| Layer: Bottom Overlay | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) Project Code: EPS2 | |
| Date: 23/10/2022 | Version: v0.2 |
| Size: A4 | |

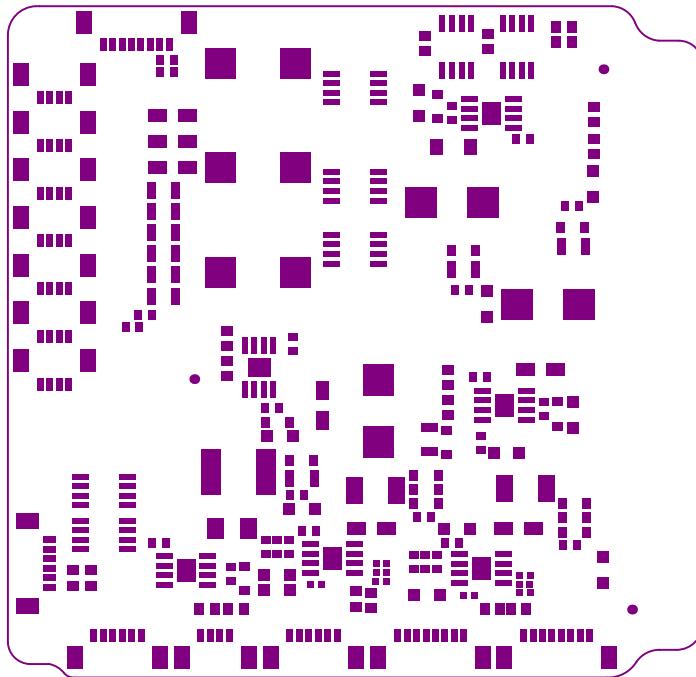
A

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A



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D

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

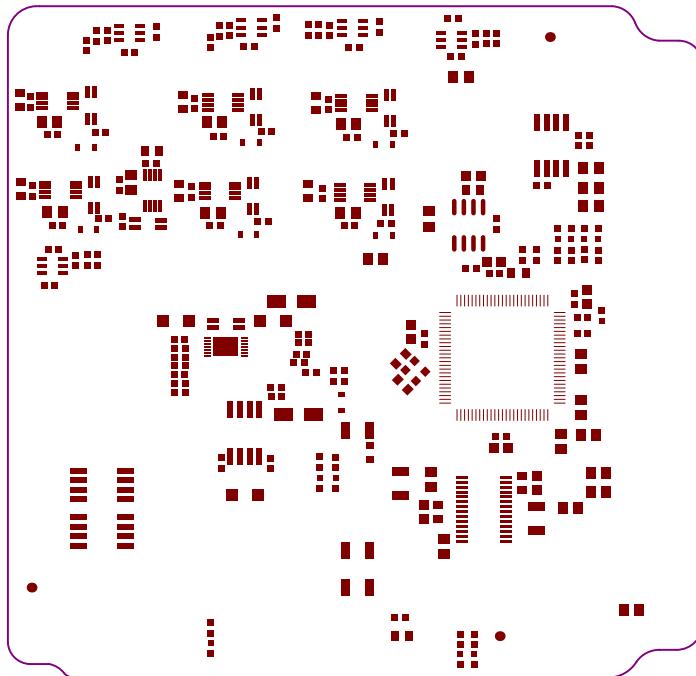
- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Top Paste | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | |
| Date: 23/10/2022 | Project Code: EPS2 |
| Version: v0.2 | Size: A4 |

A



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| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

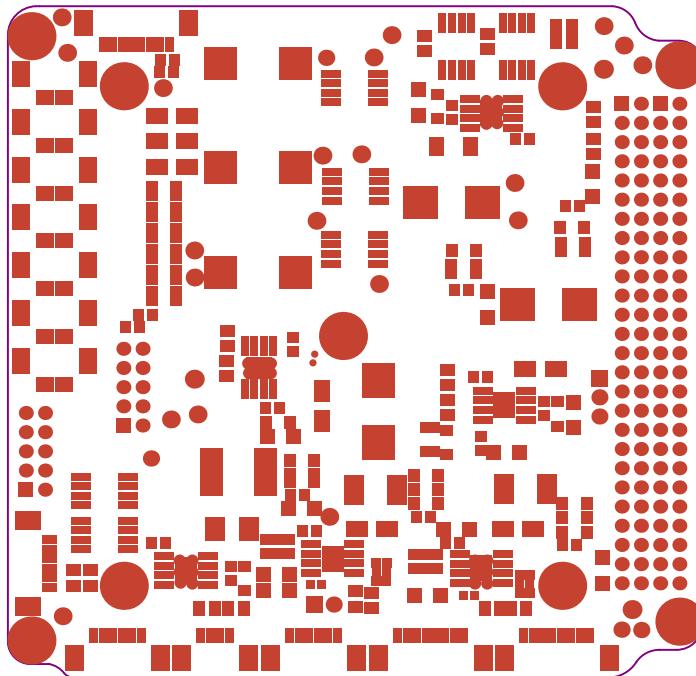
- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Bottom Paste | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | |
| Date: 23/10/2022 | Project Code: EPS2 |
| Version: v0.2 | Size: A4 |

A



B

C

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D

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

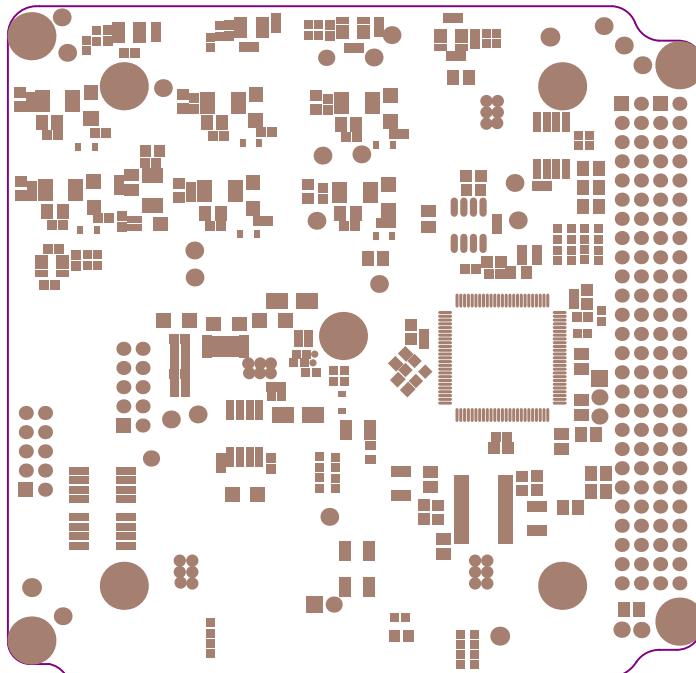
- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Top Solder | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | |
| Date: 23/10/2022 | Project Code: EPS2 |
| Version: v0.2 | Size: A4 |

A



B

C

D

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

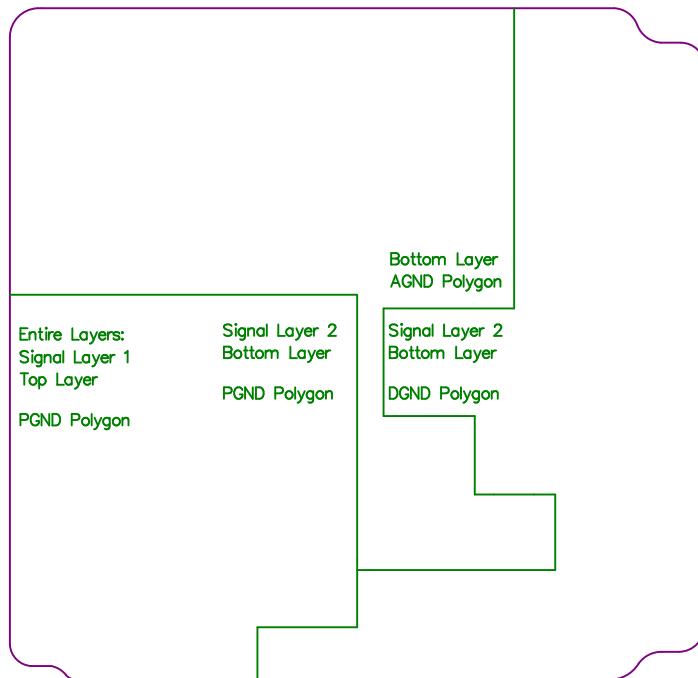
- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Bottom Solder | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | Project Code: EPS2 |
| Date: 23/10/2022 | Version: v0.2 |
| | Size: A4 |

A



B

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

A

B

C

D

Fabrication specifications:

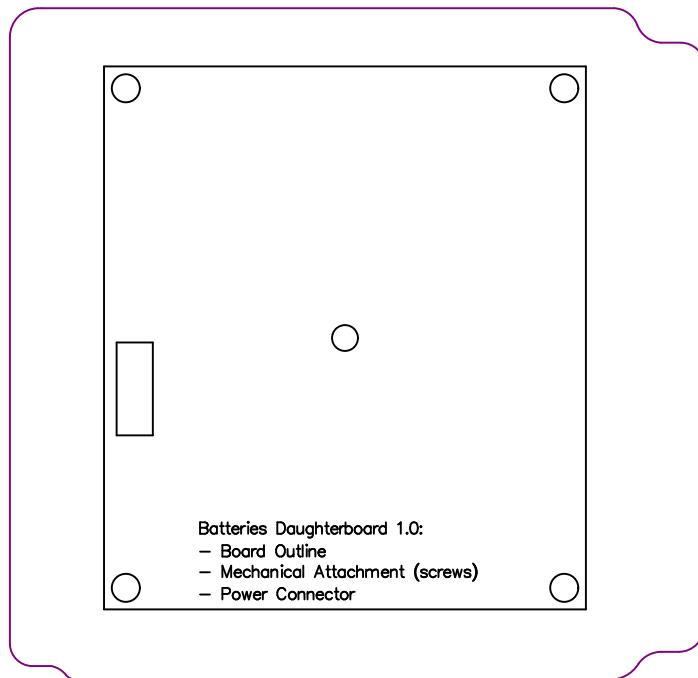
- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Grounding Splits | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | |
| Date: 23/10/2022 | Project Code: EPS2 |
| Version: v0.2 | Size: A4 |

A



B

C

D

A

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D

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

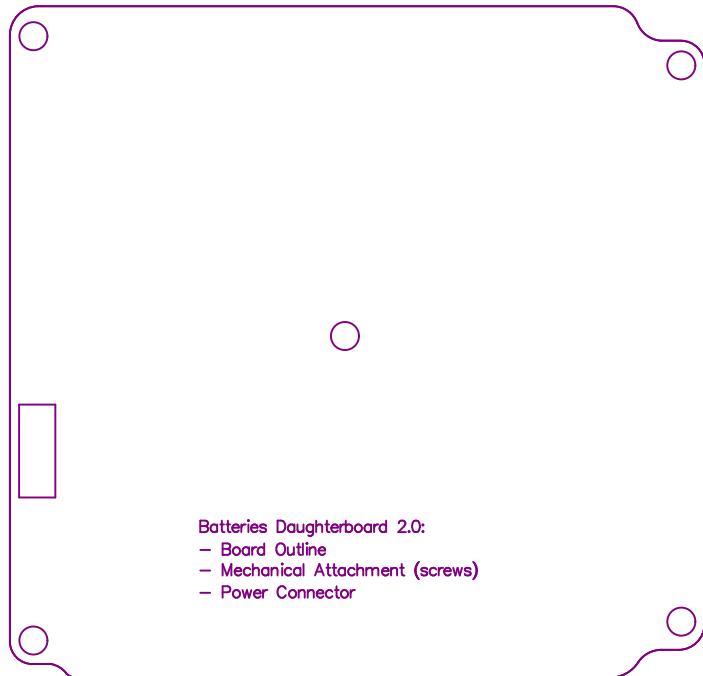
- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Batteries Board 1.0 | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | |
| Date: 23/10/2022 | Project Code: EPS2 |
| Version: v0.2 | Size: A4 |

A



B

C

D

A

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C

D

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

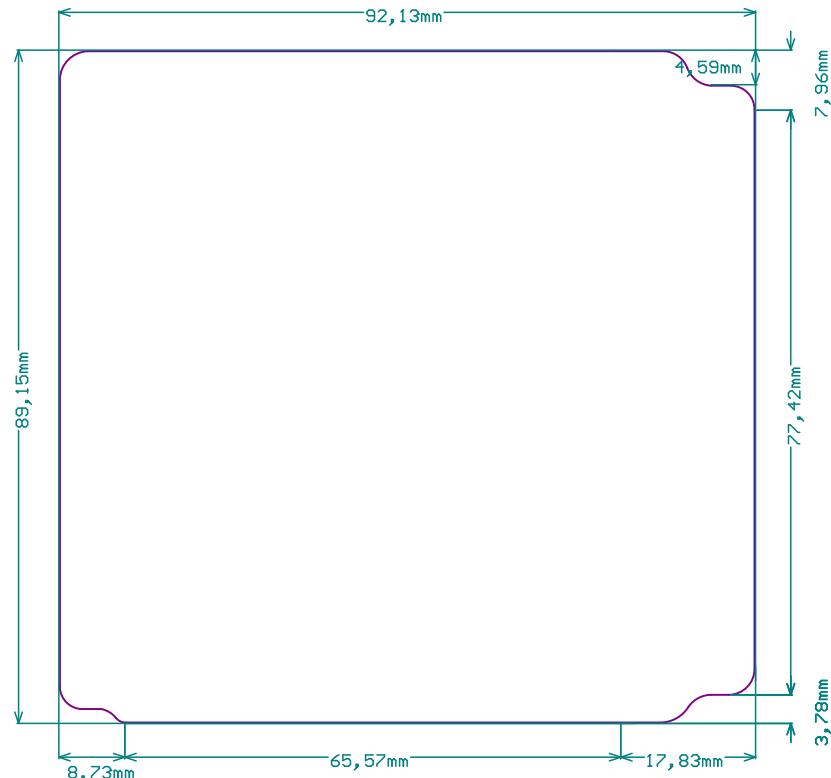
- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Batteries Board 2.0 | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | Project Code: EPS2 |
| Date: 23/10/2022 | Version: v0.2 |
| | Size: A4 |

A



A

B

B

C

C

D

D

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina



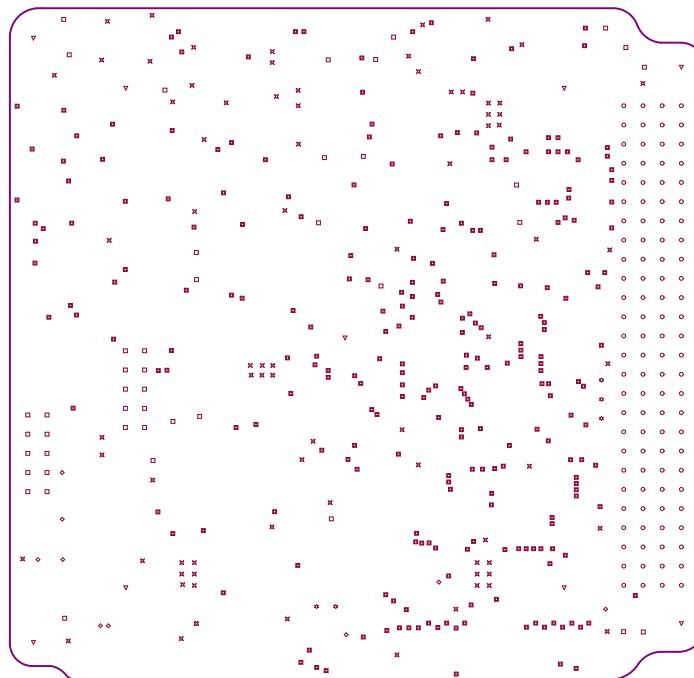
Project: EPS2

Layer: Dimension

Designed by: Andre M. P. Mattos (based on FSat-I EPS) Project Code: EPS2

Date: 23/10/2022 Version: v0.2 Size: A4

A



B

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

C

| Symbol | Count | Hole Size | Plated | Hole Type | Drill Layer Pair | Via/Pad |
|-----------|-------|---------------------|--------|-----------|--------------------------|---------|
| ☒ | 1 | 0,600mm (23,62mil) | PTH | Round | Top Layer - Bottom Layer | Via |
| ✧ | 5 | 0,991mm (39,00mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| ◇ | 9 | 0,381mm (15,00mil) | PTH | Round | Top Layer - Bottom Layer | Via |
| ▽ | 9 | 3,200mm (125,98mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| □ | 44 | 1,000mm (39,37mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| ✗ | 77 | 0,711mm (28,00mil) | PTH | Round | Top Layer - Bottom Layer | Via |
| ○ | 104 | 0,900mm (35,43mil) | PTH | Round | Top Layer - Bottom Layer | Pad |
| ■ | 253 | 0,300mm (11,81mil) | PTH | Round | Top Layer - Bottom Layer | Via |
| 502 Total | | | | | | |

Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

D

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Drill Drawing | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | |
| Date: 23/10/2022 | Project Code: EPS2 |
| Version: v0.2 | Size: A4 |

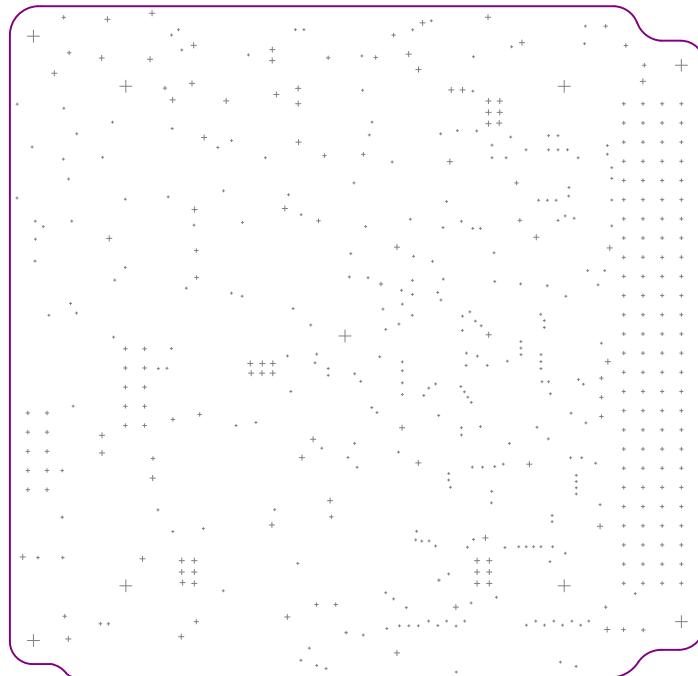
A

B

C

D

A



B

C

D

A

B

C

D

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0,010mm | 3.5 | |
| 1 | Top Layer | | 0,035mm | | |
| | Dielectric 1 | | 0,110mm | 4.2 | |
| 2 | Signal Layer 1 | | 0,035mm | | |
| | Core | FR-4 | 1,200mm | 4.2 | |
| 3 | Signal Layer 2 | | 0,036mm | | |
| | Dielectric 2 | | 0,110mm | 4.2 | |
| 4 | Bottom Layer | | 0,035mm | | |
| | Bottom Solder | Solder Resist | 0,010mm | 3.5 | |
| | Bottom Overlay | | | | |

Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4-Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Green
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

| | |
|---|---|
| SpaceLab - Federal University of Santa Catarina |  |
| Project: EPS2 | |
| Layer: Drill Guide | |
| Designed by: Andre M. P. Mattos (based on FSat-I EPS) | |
| Date: 23/10/2022 | Project Code: EPS2 |
| Version: v0.2 | Size: A4 |